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SCES809A - MARCH 2010-REVISED MAY 2010

16-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

Check for Samples: SN74AVCB164245-Q1

FEATURES

- Qualified for Automotive Applications
- Member of the Texas Instruments Widebus™
 Family
- DOC[™] Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCB} Voltage
- If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over Full 1.4-V to 3.6-V Power-Supply Range
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 750-V Charged-Device Model (C101)

DESCRIPTION

This 16-bit (dual-octal) noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCB164245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCB164245 is designed so that the control pins (1DIR, 2DIR, 1OE, and 2OE) are supplied by V_{CCB}.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CCB} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either V_{CC} input is at GND, both ports are in the high-impedance state.

ORDERING INFORMATION⁽¹⁾

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP - DGG	Tape and reel	CAVCB164245QDGGRQ1	AVCB164245Q

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

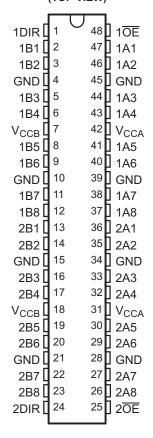


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TERMINAL ASSIGNMENTS

DGG PACKAGE (TOP VIEW)

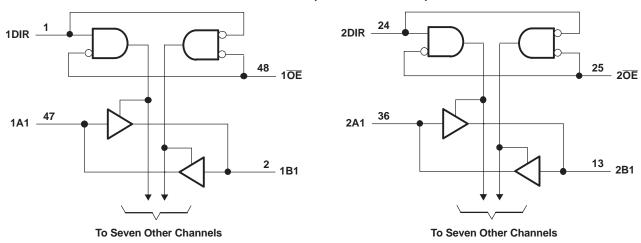


FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation



LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DGG and DGV packages.

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CCA}	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
\/	Voltage range applied to any output in the high-impedance or power-off	A port	-0.5	4.6	V
Vo	state ⁽²⁾	B port	-0.5	4.6	V
\/	Voltage range applied to any output in the high ar law state (2) (3)	A port	-0.5	V _{CCA} + 0.5	V
Vo	Voltage range applied to any output in the high or low state (2) (3)	B port	-0.5	V _{CCB} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CCA} , V _{CCB} , or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package		70	°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

 ⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 (3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



Recommended Operating Conditions (1) (2) (3)

over operating free-air temperature range (unless otherwise noted)

			V _{CCI}	V _{cco}	MIN	MAX	UNIT
V_{CCA}	Supply voltage				1.4	3.6	V
V _{CCB}	Supply voltage				1.4	3.6	V
			1.4 V to 1.95 V		V _{CCI} × 0.65		
V_{IH}	High-level input voltage	Data inputs	1.95 V to 2.7 V		1.7		V
			2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			V _{CCI} × 0.35	
V_{IL}	Low-level input voltage	Data inputs	1.95 V to 2.7 V			0.7	V
			2.7 V to 3.6 V			0.8	
			1.4 V to 1.95 V		V _{CCB} × 0.65		
V_{IH}	High-level input voltage	Control inputs (referenced to V _{CCB})	1.95 V to 2.7 V		1.7		V
		(referenced to ACCB)	2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			V _{CCB} × 0.35	
V_{IL}	Low-level input voltage	Control inputs (referenced to V _{CCB})	1.95 V to 2.7 V			0.7	V
		(referenced to vCCB)	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
	Output valtage	Active state			0	V _{cco}	V
V_O	Output voltage	3-state			0	3.6	V
				1.4 V to 1.6 V		-2	
	LPak lavel sylvet syveset			1.65 V to 1.95 V		-4	
I _{OH}	High-level output current			2.3 V to 2.7 V		-8	mA
				3 V to 3.6 V		-12	
				1.4 V to 1.6 V		2	
	Levelevel entent entered			1.65 V to 1.95 V		4	
I _{OL}	Low-level output current			2.3 V to 2.7 V		8	mA
				3 V to 3.6 V		12	,
Δt/Δν	Input transition rise or fall	rate				5	ns/V
T _A	Operating free-air tempera	ature			-40	125	°C

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 V_{CCI} is the V_{CC} associated with the data input port. V_{CCO} is the V_{CC} associated with the data output port. All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



Electrical Characteristics (1) (2)

over operating free-air temperature range (unless otherwise noted)

DAD	AMETER	TEST CONDI	LIONS	V	V		-40°C to			40°C to 1	125°C	UNIT
FAR	AIVIETER	TEST CONDI	IONS	V _{CCA}	V _{CCB}	MIN	TYP ⁽³⁾	MAX	MIN	TYP ⁽³⁾	MAX	UNIT
		I _{OH} = -100 μA	$V_{I} = V_{IH}$	1.4 V to 3.6 V	1.4 V to 3.6 V	V _{CCO} – 0.2			V _{CCO} – 0.2			
		$I_{OH} = -2 \text{ mA}$	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			1.05			
V _{OH}		$I_{OH} = -4 \text{ mA}$	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			1.2			V
		$I_{OH} = -8 \text{ mA}$	$V_I = V_{IH}$	2.3 V	2.3 V	1.75			1.75			
		$I_{OH} = -12 \text{ mA}$	$V_{I} = V_{IH}$	3 V	3 V	2.3			2.3			
		I _{OH} = 100 μA	$V_{I} = V_{IL}$	1.4 V to 3.6 V	1.4 V to 3.6 V			0.2			0.2	
. ,		$I_{OH} = 2 \text{ mA}$	$V_I = V_{IL}$	1.4 V	1.4 V			0.35			0.35	.,
V_{OL}		I _{OH} = 4 mA	$V_I = V_{IL}$	1.65 V	1.65 V			0.45			0.45	V
		I _{OH} = 8 mA	$V_{I} = V_{IL}$	2.3 V	2.3 V			0.55			0.55	
		I _{OH} = 12 mA	$V_{I} = V_{IL}$	3 V	3 V			0.7			0.7	
l _l	Control inputs	$V_I = V_{CCB}$ or GND		1.4 V to 3.6 V	3.6 V			±2.5			±2.5	μА
	A port	\\ or\\ \\ 0 to 2.6\\		0 V	0 to 3.6 V			±10			±10	
l _{off}	B port	V_I or $V_O = 0$ to 3.6 V		0 to 3.6 V	0 V			±10			±10	μΑ
. (4)	A or B ports	$V_0 = V_{CCO}$ or GND,	OE = V _{IH}	3.6 V	3.6 V			±12.5			±12.5	
I _{OZ} (4)	B port	$V_I = V_{CCI}$ or GND	$\overline{OE} = don't$	0 V	3.6 V			±12.5			±12.5	μΑ
	A port		care	3.6 V	0 V			±12.5			±12.5	
				1.6 V	1.6 V			20			35	
				1.95 V	1.95 V			20			35	
laa.		$V_I = V_{CCI}$ or GND,	l ₂ = 0	2.7 V	2.7 V			30			45	μΑ
I _{CCA}		VI = VCCI OI OIVD,	10 – 0	0 V	3.6 V			-40			-50	μΑ
				3.6 V	0 V			40			50	
				3.6 V	3.6 V			40			50	
				1.6 V	1.6 V			20			35	
				1.95 V	1.95 V			20			35	
I _{CCB}		$V_I = V_{CCI}$ or GND,	$I_0 = 0$	2.7 V	2.7 V			30			45	μА
·CCR		1 - 100 0 0 00,	.0 = 3	0 V	3.6 V			40			50	μιτ
				3.6 V	0 V			-40			-50	
				3.6 V	3.6 V			40			50	
Ci	Control inputs	V _I = 3.3 V or GND		3.3 V	3.3 V		4			4		pF
C _{io}	A or B ports	$V_O = 3.3 \text{ V or GND}$		3.3 V	3.3 V		5			5		pF

 V_{CCO} is the V_{CC} associated with the output port. V_{CCI} is the V_{CC} associated with the input port. All typical values are at T_A = 25°C. For I/O ports, the parameter I_{OZ} includes the input leakage current.



Switching Characteristics

 $T_A = -40$ °C to 85°C, $V_{CCA} = 1.5 \text{ V} \pm 0.1 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = 1 ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	6.7	1.9	6.3	1.8	5.5	1.7	5.8	20
t _{pd}	В	А	1.8	6.8	2.2	7.4	2.1	7.6	2.1	7.3	ns
	ŌE	А	2.5	8.4	2.4	7.4	2.1	5.2	1.9	4.2	20
t _{en}	OE	В	2.1	9	2.9	9.8	3.2	10	3	9.8	ns
4	ŌĒ	А	2.2	6.9	2.3	6.1	1.3	3.6	1.3	3	20
t _{dis}	OE -	В	2.1	7.1	2.3	6.4	1.7	5.1	1.6	4.8	ns

Switching Characteristics

 $T_A = -40$ °C to 125°C, $V_{CCA} = 1.5 \text{ V} \pm 0.1 \text{ V}$ (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	12.7	1.9	12.3	1.8	11.5	1.7	11.8	20
t _{pd}	В	Α	1.8	12.8	2.2	13.4	2.1	13.6	2.1	13.3	ns
	ŌE	Α	2.5	14.4	2.4	13.4	2.1	11.2	1.9	10.2	
t _{en}	OE	В	2.1	15	2.9	15.8	3.2	16	3	15.8	ns
	ŌĒ	А	2.2	12.9	2.3	12.1	1.3	9.6	1.3	9	20
t _{dis}	OE	В	2.1	13.1	2.3	12.4	1.7	11.1	1.6	10.8	ns

Switching Characteristics

 $T_A = -40$ °C to 85°C, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = ± 0.1		± 0.15 V		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	6.7	1.8	6	1.7	4.7	1.6	4.3	
t _{pd}	В	А	1.4	5.5	1.8	6	1.8	5.8	1.8	5.5	ns
	ŌĒ	А	2.6	8.5	2.5	7.5	2.2	5.3	1.9	4.2	
t _{en}	OE	В	1.8	7.6	2.6	7.7	2.6	7.6	2.6	7.4	ns
	ŌĒ	А	2.3	7	2.3	6.1	1.3	3.6	1.3	3	
t _{dis}	OE .	В	1.8	7	2.5	6.3	1.8	4.7	1.7	4.4	ns

Switching Characteristics

 $T_A = -40$ °C to 125°C, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CCB} = 1.5 V ± 0.1 V		1.8 V 5 V	V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	12.7	1.8	12	1.7	10.7	1.6	10.3	
t _{pd}	В	Α	1.4	11.5	1.8	12	1.8	11.8	1.8	11.5	ns
	ŌĒ	Α	2.6	14.5	2.5	13.5	2.2	11.3	1.9	10.2	
t _{en}	OE	В	1.8	13.6	2.6	13.7	2.6	13.6	2.6	13.4	ns
1	ŌĒ	Α	2.3	13	2.3	12.1	1.3	9.6	1.3	9	
t _{dis}	OE	В	1.8	13	2.5	12.3	1.8	10.7	1.7	10.4	ns

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Switching Characteristics

 $T_A = -40$ °C to 85°C, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = ± 0.3	UNIT	
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.6	6	1.8	5.6	1.5	4	1.4	3.4	20
t _{pd}	В	А	1.3	4.6	1.7	4.4	1.5	4	1.4	3.7	ns
	ŌĒ	А	3.1	8.5	2.5	7.5	2.2	5.3	1.9	4.2	
t _{en}	OE	В	1.7	5.7	2.2	5.5	2.2	5.3	2.2	5.1	ns
	ŌĒ	А	2.4	7	3	6.1	1.4	3.6	1.2	3	20
t _{dis}	OE	В	1.2	5.8	1.9	5	1.4	3.6	1.3	3.3	ns

Switching Characteristics

 $T_A = -40$ °C to 125°C, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.6	12	1.8	11.6	1.5	10	1.4	9.4	20
t _{pd}	В	Α	1.3	10.6	1.7	10.4	1.5	10	1.4	9.7	ns
	ŌE	Α	3.1	14.5	2.5	13.5	2.2	11.3	1.9	10.2	
t _{en}	OE	В	1.7	11.7	2.2	11.5	2.2	11.3	2.2	11.1	ns
	ŌĒ	А	2.4	13	3	12.1	1.4	9.6	1.2	9	20
t _{dis}	OE	В	1.2	11.8	1.9	11	1.4	9.6	1.3	9.3	ns

Switching Characteristics

 $T_A = -40$ °C to 85°C, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 1 ± 0.2		V _{CCB} = 3 ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
•	Α	В	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	
t _{pd}	В	А	1.3	4.5	1.6	3.8	1.5	3.3	1.4	3.1	ns
	ŌĒ	А	2.6	8.3	2.5	7.4	2.2	5.2	1.9	4.1	20
t _{en}	OE	В	1.6	4.9	2	4.5	2	4.3	1.9	4.1	ns
	ŌĒ	Α	2.3	7	3	6	1.3	3.5	1.2	3.5	20
t _{dis}	OE	В	1.3	6.9	2.1	5.5	1.6	3.8	1.5	3.5	ns

Switching Characteristics

 $T_A = -40^{\circ}\text{C}$ to 125°C, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0.15		V _{CCB} = 2 ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	А	В	1.5	11.9	1.7	11.4	1.5	9.7	1.4	9.1	
t_{pd}	В	А	1.3	10.5	1.6	9.8	1.5	9.3	1.4	9.1	ns
	ŌĒ	А	2.6	14.3	2.5	13.4	2.2	11.2	1.9	10.1	20
t _{en}	OE	В	1.6	10.9	2	10.5	2	10.3	1.9	10.1	ns
t _{dis}	ŌĒ	А	2.3	13	3	12	1.3	9.5	1.2	9.5	
	OE	В	1.3	12.9	2.1	11.5	1.6	9.8	1.5	9.5	ns

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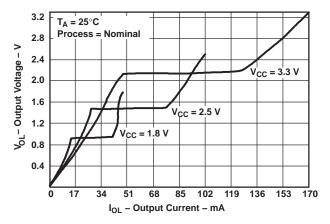
Operating Characteristics

 V_{CCA} and V_{CCB} = 3.3 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT	
	Power dissipation capacitance per transceiver,	Outputs enabled		14	
C _{pdA}	A-port input, B-port output	Outputs disabled	C 0 f 10 MHz	7	
(V _{CCA}) Power dissipation capacitance per transceiver,		Outputs enabled	$C_L = 0$, $f = 10 \text{ MHz}$	20	pF
	B-port input, A-port output	Outputs disabled		7	
	Power dissipation capacitance per transceiver,	Outputs enabled		20	ָר
C _{pdB}	A-port input, B-port output	Outputs disabled	$C_1 = 0$. $f = 10 \text{ MHz}$	7	
C_{pdB} (V_{CCB})	Power dissipation capacitance per transceiver,	Outputs enabled	$C_L = 0$, $f = 10 \text{ MHz}$	14	pF
	B-port input, A-port output	Outputs disabled		7	

Output Description

The DOCTM circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOCTM) Circuitry Technology and Applications, literature number SCEA009.



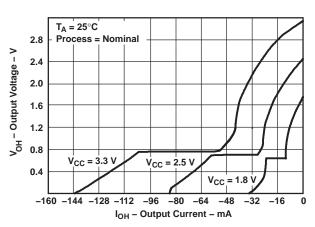
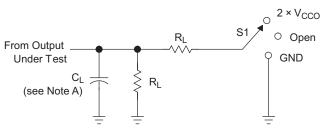


Figure 1. Typical Output Voltage vs Output Current

 V_{CCB}



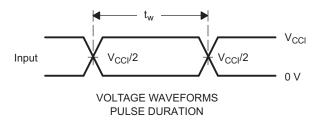
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	2 × V _{CCO}
t _{PHZ} /t _{PZH}	GND

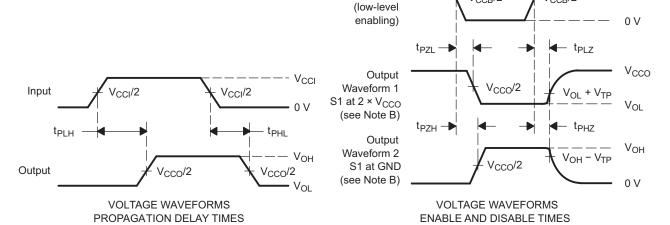
LOAD CIRCUIT

V _{CCO}	C _L	R _L	V _{TP}
1.5 V ± 0.1 V	15 pF	500 Ω	0.1 V
1.8 V ± 0.15 V	30 pF	500 Ω	0.15 V
$2.5 V \pm 0.2 V$	30 pF	500 Ω	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	30 pF	500 Ω	0.3 V



V_{CCB}/2

V_{CCB}/2



Output Control

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, $Z_0 = 50 \Omega$, $dv/dt \ge 1 V/ns$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. V_{CCI} is the V_{CC} associated with the input port.
 - I. V_{CCO} is the V_{CC} associated with the output port.

Figure 2. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CAVCB164245QDGGRQ1	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AVCB164245Q
CAVCB164245QDGGRQ1.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AVCB164245Q

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74AVCB164245-Q1:

Catalog: SN74AVCB164245

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

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● Enhanced Product : SN74AVCB164245-EP

NOTE: Qualified Version Definitions:

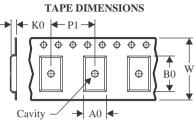
- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

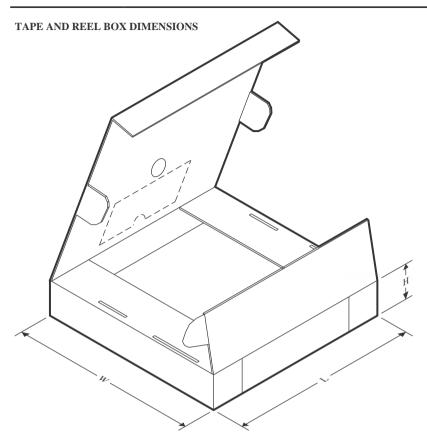


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAVCB164245QDGGRQ1	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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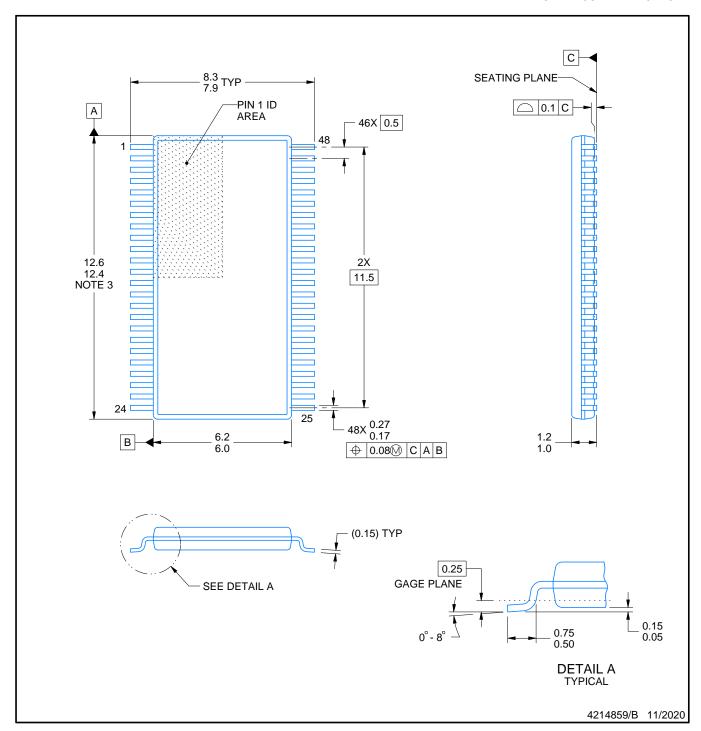


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CAVCB164245QDGGRQ1	TSSOP	DGG	48	2000	356.0	356.0	45.0	



SMALL OUTLINE PACKAGE



NOTES:

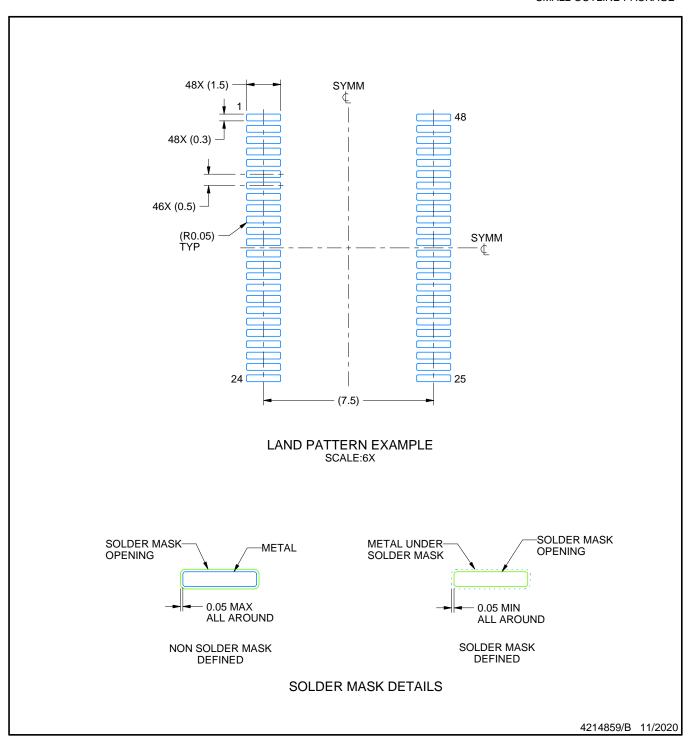
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

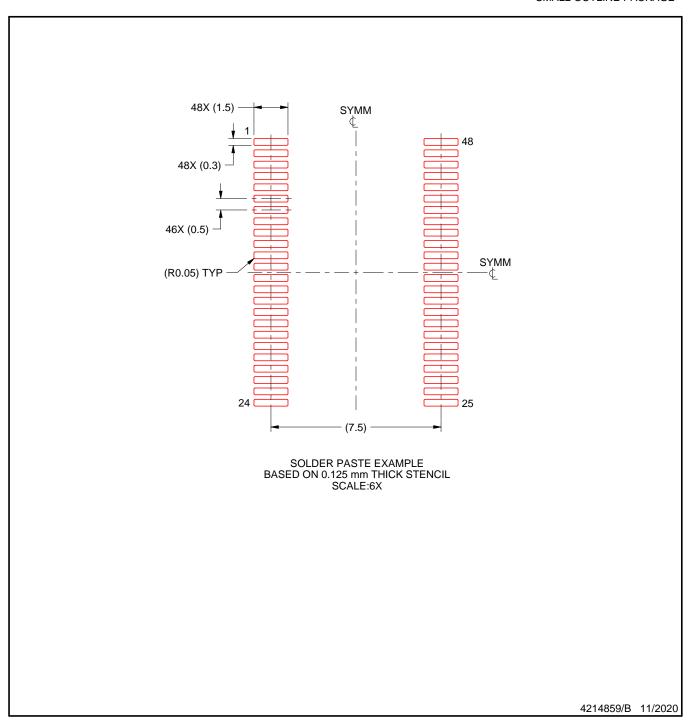


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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